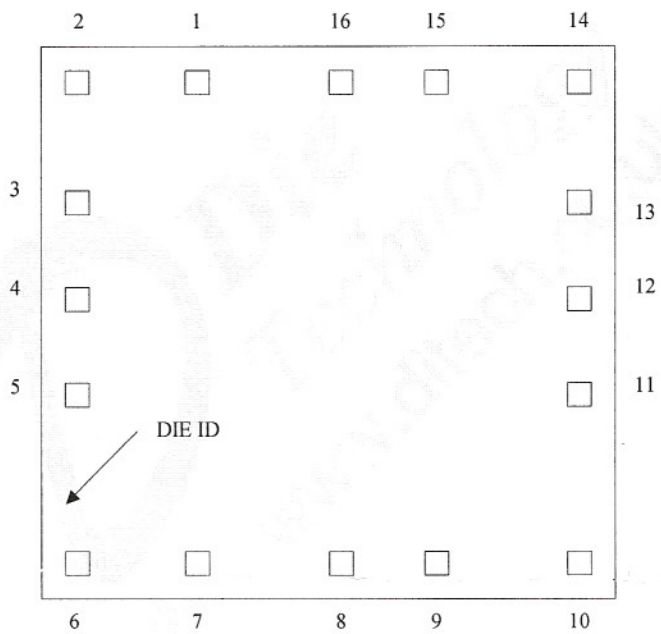
ISO9001:2000 Certified SCI Quality System

# Sierra Components, Inc.

**2222 Park Place Building 3 Suite E • Minden, Nevada 89423**
Phone: 775.783.4940 Fax: 775.783.4947




**PAD FUNCTIONS**

| | |
|---|---|
| 1 | NOT E |
| 2 | A |
| 3 | B |
| 4 | Q0 |
| 5 | Q1 |
| 6 | Q2 |
| 7 | Q3 |
| 8 | VSS |
| 9 | Q3 |
| 10 | Q2 |
| 11 | Q1 |
| 12 | Q0 |
| 13 | B |
| 14 | A |
| 15 | NOT E |
| 16 | VDD |

The information given is believed to be correct at the time of issue.
Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.
Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

**Note: 1 mil = 0.001inch**

APPROVED

BEN WHITE

.....

DATE: 19/5/2004

# CD4555B

TI

DIE INFORMATION

DIMENSIONS (Mils): 70 x 67 x 25
BOND PADS (Mils):
MASK. REF: CD4555B
GEOMETRY:
BACK POTENTIAL: VCC

METALLISATION

TOP: Al
BACK: Si